

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SC70 FLIPCHIP

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**TOTAL MASS (g) : 0.010578**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000851	1000000	80449.0859375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.003032	975000	286629.40625		
		Iron (Fe)	7439-89-6	0.000075	24000	7090.10742188		
		Phosphorus (P)	7723-14-0	0.000001	300	94.5347671509		
		Zinc (Zn)	7440-66-6	0.000002	700	189.069534302		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003110</b>	<b>1000000</b>	<b>294003.09375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003408	1000000	322185.78125		
		<b>External Plating Total:</b>				<b>0.003408</b>	<b>1000000</b>	<b>322185.78125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
		<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>
Die Attach	SnAg Cap	Silver (Ag)	7440-22-4	0.000013	20000	1228.95202637		
		Tin (Sn)	7440-31-5	0.000656	980000	62014.8046875		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000000	0	0		
<b>Die Attach Total:</b>				<b>0.000669</b>	<b>1000000</b>	<b>63243.7539062</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000147	58000	13896.6103516		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.002261	890000	213743.109375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000127	50000	12005.9160156		
		Carbon Black (C)	1333-86-4	0.000005	2000	472.673797607		
		<b>Encapsulation Total:</b>				<b>0.002540</b>	<b>1000000</b>	<b>240118.296875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000000	0	0		
					<b>TOTAL MASS (g) :</b>	<b>0.010578</b>		